Unit: mm

TOSHIBA Field Effect Transistor Silicon P/N-Channel MOS Type (P-Channel N-Channel Ultra-High-Speed U-MOSIII)

# TPC8406-H

High Efficiency DC/DC Converter Applications

Notebook PC Applications

Portable Equipment Applications

**CCFL Inverter Applications** 

Small footprint due to a small and thin package

High speed switching

Low drain-source ON-resistance: P-Channel RDS (ON) =  $24 \text{ m}\Omega$  (typ.)

N-Channel RDS (ON) =  $22 \text{ m}\Omega$  (typ.)

Small gate charge: P-Channel QSW = 9.7 nC (typ.)

N-Channel Qsw = 3.5 nC (typ.)

High forward transfer admittance: P-Channel  $|Y_{fs}| = 13 \text{ S (typ.)}$ 

N-Channel  $|Y_{fs}| = 14 \text{ S (typ.)}$ 

Low leakage current: P-Channel IDSS =  $-10 \mu A (V_{DS} = -40 V)$ 

N-Channel IDSS =  $10 \mu A (V_{DS} = 40 V)$ 

Enhancement mode

: P-Channel  $V_{th}$  = -0.8 to -2.0 V ( $V_{DS}$  = -10 V,  $I_{D}$  = -1 mA)

: N-Channel  $V_{th} = 1.1 \text{ to } 2.3 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$ 

# Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rat	Unit		
	Syllibol	P-Channel	N-Channel	Offic		
Drain-source v	V <sub>DSS</sub>	-40	40	V		
Drain-gate vol	$V_{DGR}$	-40	40	V		
Gate-source v	oltage	V <sub>GSS</sub>	±20	±20	V	
Drain current	DC (Note 1)	ΙD	-6.5	6.5	Α	
Diaili Cuileiil	Pulse (Note 1)	I <sub>DP</sub>	-26	26	^	
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D(1)</sub>	1.5	1.5	W	
(t = 10s) (Note 2a)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	1.1	1.1		
Drain power dissipation	Single-device operation (Note 3a)	P <sub>D(1)</sub>	0.75	0.75		
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 3b)	P <sub>D(2)</sub>	0.45	0.45		
Single-pulse avalanche energy		E <sub>AS</sub>	19 (Note 4a)	19 (Note 4b)	mJ	
Avalanche cur	I <sub>AR</sub>	-6.5	6.5	Α		
Repetitive avalanche energy Single-device value at operation (Note 2a, 3b, 5)		E <sub>AR</sub>	0.08		mJ	
Channel temperature		T <sub>ch</sub>	15	150		
Storage temper	T <sub>stg</sub>	–55 t	-55 to 150			

0.4±0.1 ⊕ 0.25 ₪ 0.595TYP 1.27 5.5MAX 5.0±0.2 SOURCE **GATE** 5, 6

DRAIN

DRAIN

7, 8

2-6J1E

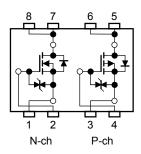
Weight: 0.085 g (typ.)

**GATE** 

**JEDEC** JEITA **TOSHIBA** 

SOURCE

## **Circuit Configuration**



Note: For Notes 1 to 5, refer to the next page.

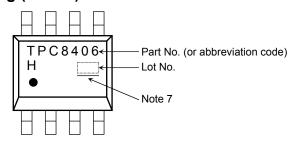
Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

This transistor is an electrostatic-sensitive device. Handle with care.

#### **Thermal Characteristics**

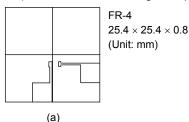
Characteristic	Symbol	Max	Unit	
Thermal resistance, channel to ambient (t = 10s) (Note 2a)	Single-device operation (Note 3a)	R <sub>th (ch-a) (1)</sub>	83.3	
	Single-device value at dual operation (Note 3b)	R <sub>th</sub> (ch-a) (2)	114	°C/W
Thermal resistance, channel to ambient	Single-device operation (Note 2a)	R <sub>th (ch-a) (1)</sub>	167	C/VV
(t = 10s) (Note 2b)	Single-device value at dual operation (Note 2b)	R <sub>th (ch-a) (2)</sub>	278	

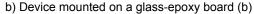
# Marking (Note 6)

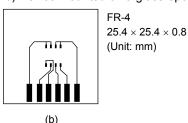


Note 1: The channel temperature should not exceed 150°C during use.

Note 2: a) Device mounted on a glass-epoxy board (a)





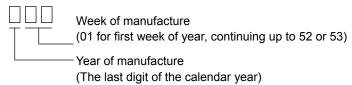


- Note 3: a) The power dissipation and thermal resistance values are shown for a single device (During single-device operation, power is applied to one device only.).
  - b) The power dissipation and thermal resistance values are shown for a single device (During dual operation, power is evenly applied to both devices.).

Note 4: a) 
$$V_{DD}=24$$
 V,  $T_{ch}=25^{\circ}C$  (initial), L = 0.5 mH,  $R_G=25$   $\Omega$ ,  $I_{AR}=6.5$  A b)  $V_{DD}=24$  V,  $T_{ch}=25^{\circ}C$  (initial), L = 0.5 mH,  $R_G=25$   $\Omega$ ,  $I_{AR}=6.5$  A

- Note 5: Repetitive rating: pulse width limited by maximum channel temperature
- Note 6: on the lower left of the marking indicates Pin 1.

\* Weekly code: (Three digits)



Note 7: A line under a Lot No. identifies the indication of product Labels.

Not underlined: [[Pb]]/INCLUDES > MCV

Underlined: [[G]]/RoHS COMPATIBLE or [[G]]/RoHS [[Pb]]

Please contact your TOSHIBA sales representative for details as to environmental matters such as the RoHS compatibility of Product. The RoHS is the Directive 2002/95/EC of the European Parliament and of the Council of 27 January 2003 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



# P-Channel Electrical Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	ent	I <sub>DSS</sub>	$V_{DS} = -40 \text{ V}, V_{GS} = 0 \text{ V}$	_	_	-10	μА
Drain course bro	akdawa valtaga	V <sub>(BR) DSS</sub>	$I_D = -10 \text{ mA}, V_{GS} = 0 \text{ V}$	-40	_	_	V
Drain-source breakdown voltage		V (BR) DSX	$I_D = -10 \text{ mA}, V_{GS} = 20 \text{ V}$	-20	_	_	\ \
Gate threshold vo	oltage	V <sub>th</sub>	$V_{DS} = -10 \text{ V}, I_D = -1 \text{ mA}$	-0.8	_	-2.0	٧
Drain-source ON	resistance	Pro (ON)	$V_{GS} = -4.5 \text{ V}, I_D = -3.3 \text{ A}$	_	29	37	mO
Diam-source Oiv	-resistance	R <sub>DS</sub> (ON)	$V_{GS} = -10 \text{ V}, I_D = -3.3 \text{ A}$	_	24	30	mΩ
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = -10 \text{ V}, I_D = -3.3 \text{ A}$	6.5	13	_	S
Input capacitance	<b>;</b>	C <sub>iss</sub>		_	1190	_	pF
Reverse transfer	capacitance	C <sub>rss</sub>	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	_	170	_	
Output capacitan	ce	Coss		_	250	_	
	Rise time	t <sub>r</sub>	$V_{GS}$ $0$ $V$ $0$ $0$ $0$ $0$ $0$ $0$ $0$ $0$ $0$ $0$	_	5	_	- ns
Cuitabina tima	Turn-on time	t <sub>on</sub>		_	12	_	
Switching time	Fall time	t <sub>f</sub>		_	12	_	
	Turn-off time	t <sub>off</sub>		_	43	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{V}$ $I_D = -6.5 \text{ A}$	_	27	_	
		Qg	$\begin{array}{l} V_{DD} \simeq -32 \; V, \; V_{GS} = -5 \; V \\ I_D = - \; 6.5 \; A \end{array} \label{eq:VDD}$	_	15	_	nC
Gate-source charge 1		Q <sub>gs1</sub>	$V_{DD} \simeq -32 \text{ V}, V_{GS} = -10 \text{ V}$ $I_{D} = -6.5 \text{ A}$	_	3.2	_	
Gate-drain ("Miller") charge		Q <sub>gd</sub>		_	8.1	_	
Gate switch char	ge	Q <sub>SW</sub>		_	9.7	_	

# Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	-26	Α
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = -6.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	1.2	V



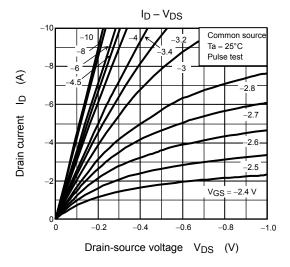
# N-channel Electrical Characteristics (Ta = 25°C)

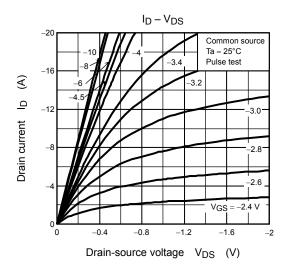
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μА
Drain cutoff curre	ent	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	_	_	10	μА
Drain agurag bro	akdawa valtaga	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	40	_	_	V
Drain-source breakdown voltage		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25	_	_	v
Gate threshold ve	oltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	1.1	_	2.3	V
Drain-source ON	ragintanca	D= 0 (01)	$V_{GS} = 4.5 \text{ V}, I_D = 3.3 \text{ A}$	_	27	35	- mΩ
Diain-source ON	-resistance	R <sub>DS</sub> (ON)	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 3.3 A	_	22	27	
Forward transfer	admittance	Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 3.3 \text{ A}$	7	14	_	S
Input capacitance	е	C <sub>iss</sub>		_	650	_	
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz	_	55	_	pF
Output capacitan	се	C <sub>oss</sub>		_	240	_	
	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10 \text{ V}}{\text{O} \text{ V}} \stackrel{\text{I}_{D} = 3.3 \text{ A}}{\text{O} \text{VOUT}} \stackrel{\text{V}_{D} = 3.3 \text{ A}}{\text{RL}} = 6.1 \Omega$ $V_{DD} \simeq 20 \text{ V}$	_	3	_	- ns
	Turn-on time	t <sub>on</sub>		_	9	_	
Switching time	Fall time	t <sub>f</sub>		_	2	_	
	Turn-off time	t <sub>off</sub>	Duty ≦ 1%, t <sub>W</sub> = 10 μs	_	18	_	
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{V}, I_D = 6.5 \text{A}$	_	11	_	
			$V_{DD} \simeq 32 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 6.5 \text{A}$		6.2		
Gate-source charge 1		Q <sub>gs1</sub>	V <sub>DD</sub> ≈ 32 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6.5A		2.1		nC
Gate-drain ("Miller") charge		Q <sub>gd</sub>			2.7		
Gate switch char	ge	Q <sub>SW</sub>		_	3.5		

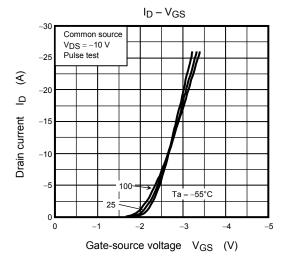
# Source-Drain Ratings and Characteristics (Ta = 25°C)

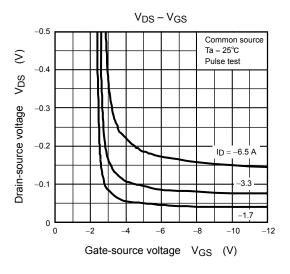
Characteristic		Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current	Pulse (Note 1)	I <sub>DRP</sub>	_	_	_	26	Α
Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V

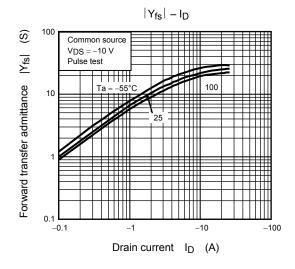
#### P-Channel

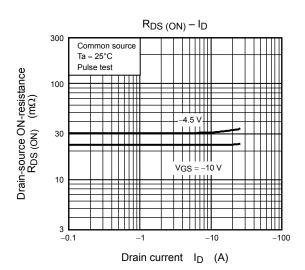




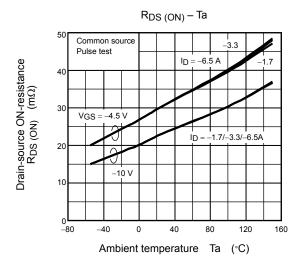


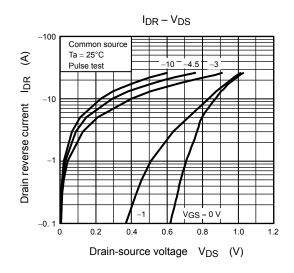


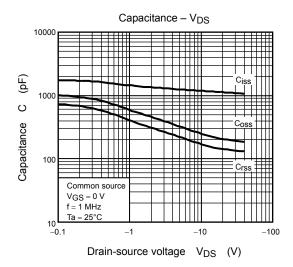


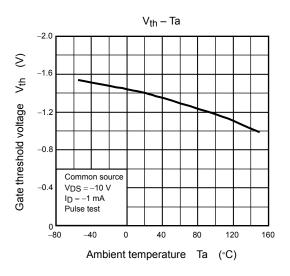


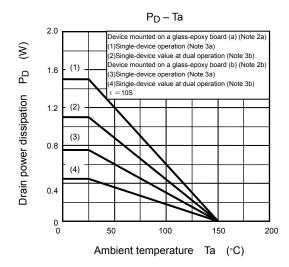
### **P-Channel**

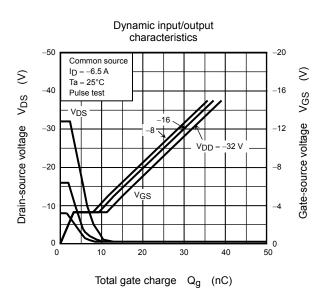






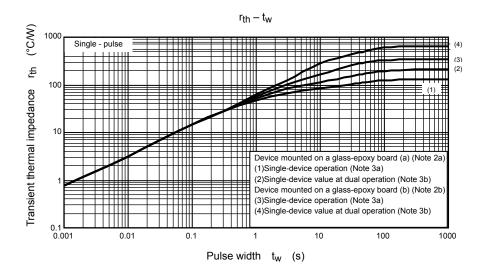




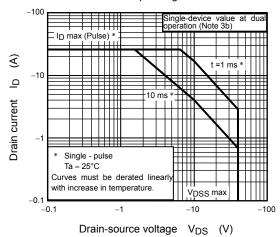


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## **P-Channel**

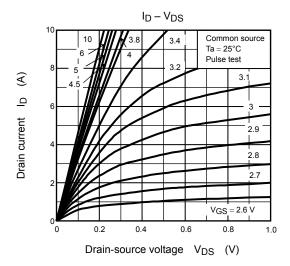


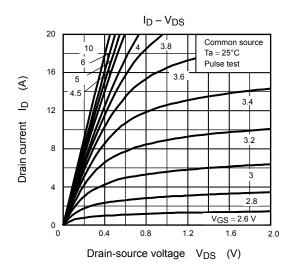
#### Safe operating area

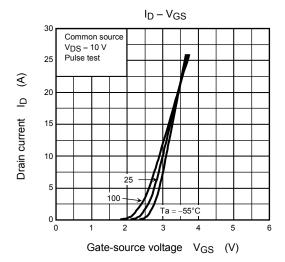


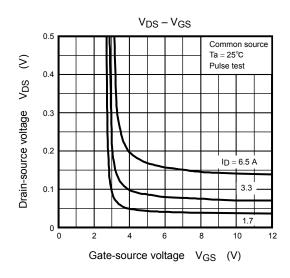
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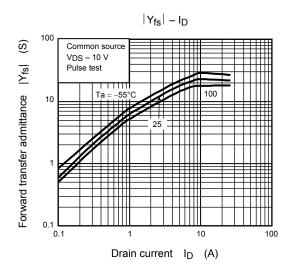
## **N-Channel**

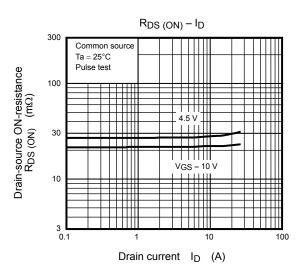




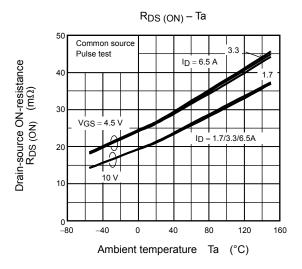


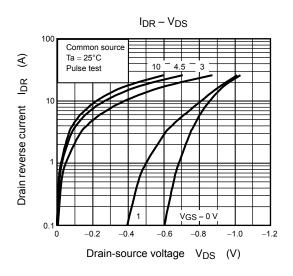


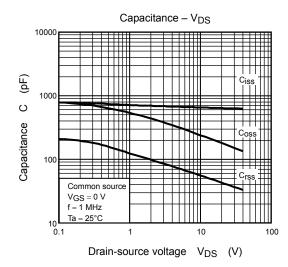


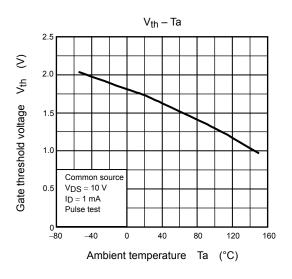


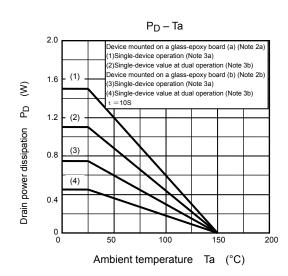
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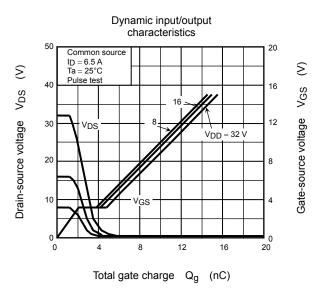




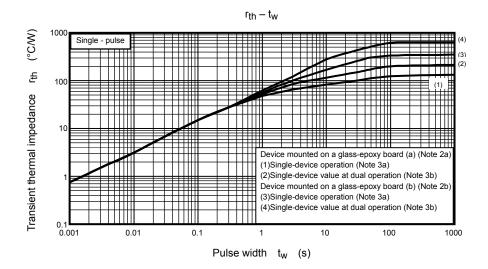




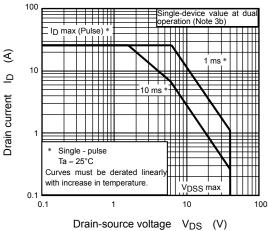




## **N-Channel**







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